



PATENT

GP/2876.
#11A
10/28/02
amr

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re U.S. Patent Application

) Art Unit: 2876

Applicant: Satoshi Kitagawa

) I hereby certify that this correspondence is being
) deposited with the United States Postal Service

Serial No.: 09/696,117

) as first class mail in an envelope addressed to:

Filed: October 25, 2000

) Commissioner of Patents, Washington, DC 20231,
) on **October 4, 2002.**

For: **MARKING METHOD FOR
SEMICONDUCTOR WAFER**

) Gerald T. Shekleton

) Gerald T. Shekleton Reg. No. 27,466

Examiner: Karl D. Frech

)

AMENDMENT

Box NON-FEE AMENDMENT

Commissioner for Patents

Washington, D.C. 20231

Dear Sir:

The Office Action of February 5, 2002 has been carefully reviewed and the following amendments
and remarks are made in response thereto:

IN THE CLAIMS:

Please amend claims 5, 6, 10, 11, and 17 to 22 as follows:

5. (Amended) The method of reproducing a mark on a semiconductor wafer according
to claim 2, wherein the predetermined mark is formed by means of a combination of dots, each dot
measuring 1 to 13 μm wide, and the substantially-effaced mark is reproduced by means of forming a
mark essentially identical with the substantially-effaced mark at another location in the vicinity fo the

10/23/2002 AMPSL 0000011 230920 09696117

01 TC:1251

110.00 CH

(Amended)

The method of reproducing a mark on a semiconductor wafer according
to claim 2, wherein the predetermined mark is a minute ID mark which is assigned to the semiconductor
wafer and is formed by means of a combination of dots, each dot measuring 1 to 13 μm wide, and the
substantially-effaced mark is reproduced by means of forming a mark essentially identical with the
substantially-effaced mark at another location in the vicinity of the substantially-effaced mark.